



**THE DATASHEET OF
CONSMA001-SMD-G-T**



Features

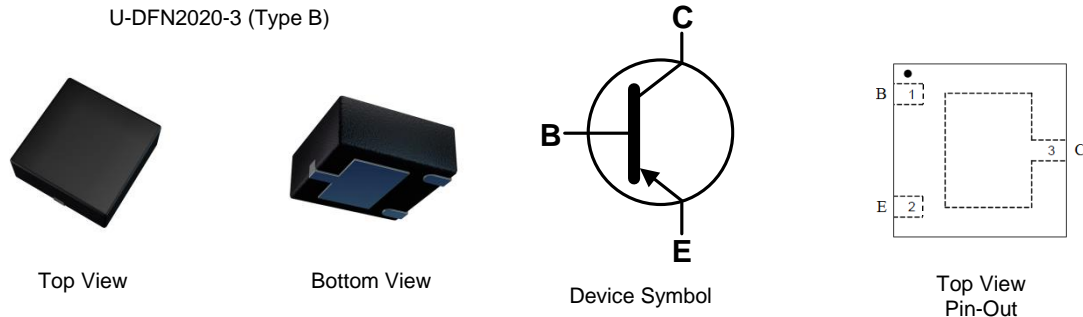
- $BV_{CEO} > -100V$
- h_{FE} Specified up to -3A for High Current Gain Hold Up
- Low Profile 0.6mm High Package for Thin Applications
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **For automotive applications requiring specific change control (i.e.: parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please refer to the related automotive grade (Q-suffix) part. A listing can be found at <https://www.diodes.com/products/automotive/automotive-products/>.**
- **This part is qualified to JEDEC standards (as references in AEC-Q) for High Reliability. <https://www.diodes.com/quality/product-definitions/>**

Mechanical Data

- Case: U-DFN2020-3 (Type B)
- Nominal Package Height: 0.6mm
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish – NiPdAu, Solderable per MIL-STD-202, Method 208 (E4)
- Weight: 0.01 grams (Approximate)

Applications

- DC-DC Converters
- Charging Circuits
- Motor Control
- Power Switches

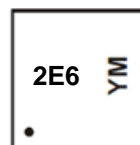


Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
DXTP58100CFDB-7	2E6	7	8	3,000

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



2E6 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: G = 2019)
 M = Month (ex: 9 = September)

Date Code Key

Year	2019	2020	2021	2022	2023	2024	2025	2026				
Code	G	H	I	J	K	L	M	N				
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Parameter	Symbol	Limit	Unit
Collector-Base Voltage	V _{CB0}	-100	V
Collector-Emitter Voltage	V _{CEO}	-100	
Emitter-Base Voltage	V _{EBO}	-7	
Peak Pulse Current	I _{CM}	-4	A
Continuous Collector Current	I _C	-2	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

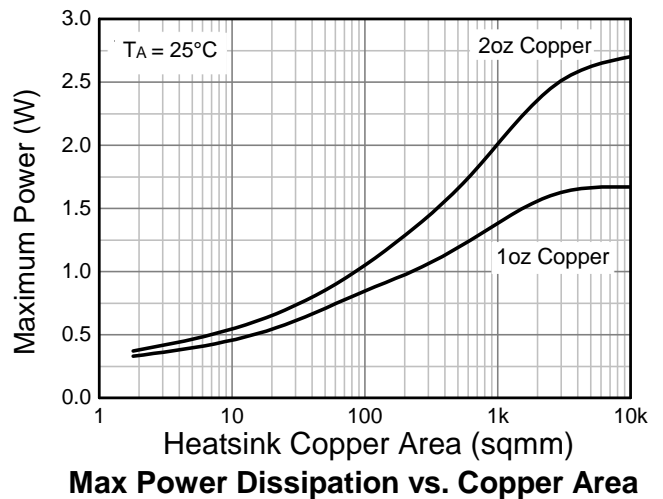
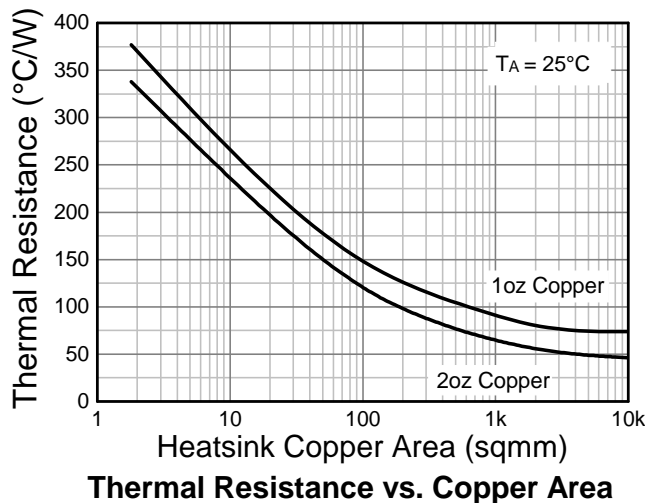
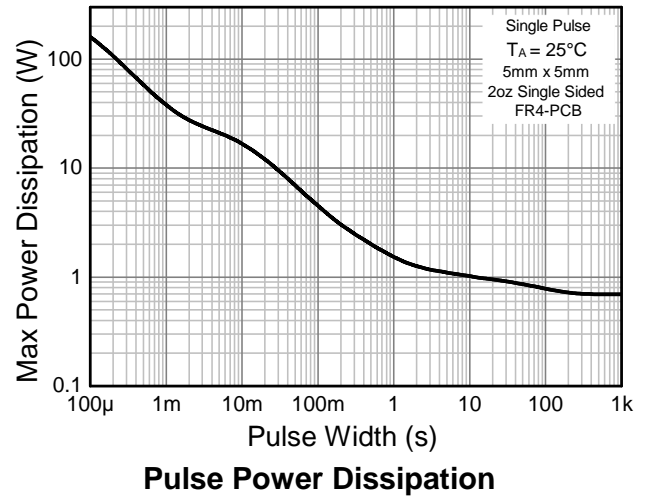
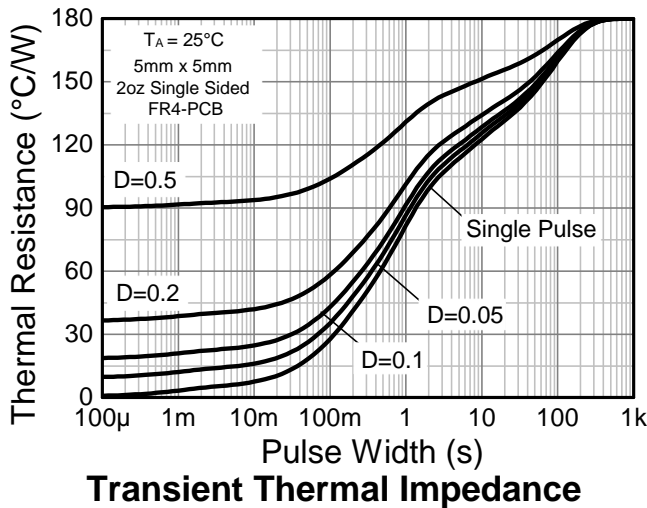
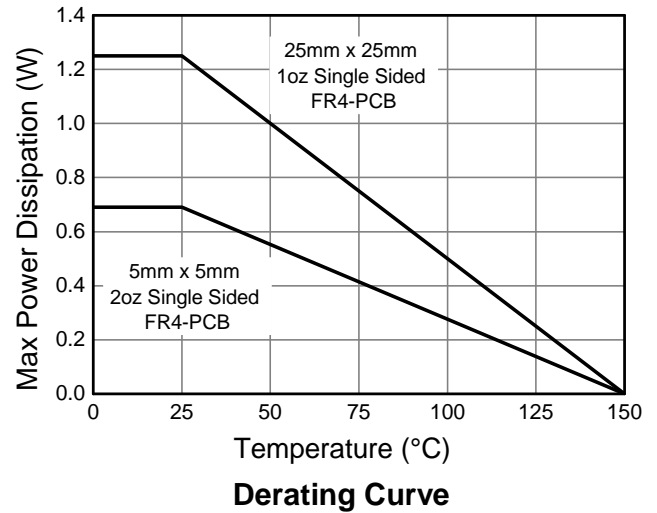
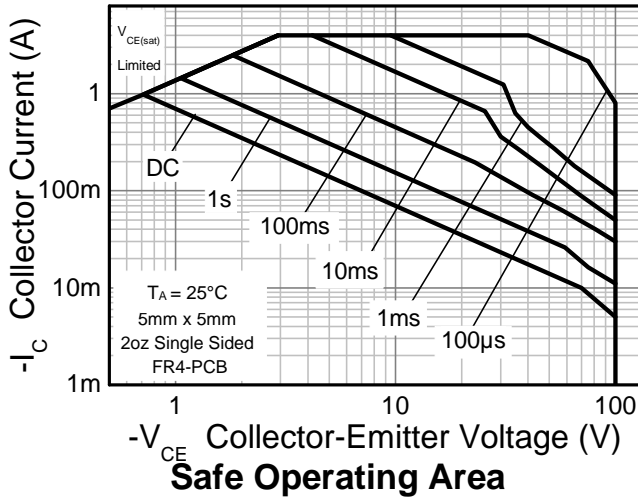
Characteristic	Symbol	Value	Unit
Power Dissipation	P _D	0.69	W
		1.25	
Thermal Resistance, Junction to Ambient	R _{θJA}	180	°C/W
		100	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the exposed collector on 5mm x 5mm 2oz copper on single sided FR4 PCB; device is measured under still air conditions whilst operating in the steady state.
 6. Same as Note (5) except the exposed collector pad is mounted on 25mm x 25mm 1oz copper.
 7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

Thermal Characteristics and Derating Information

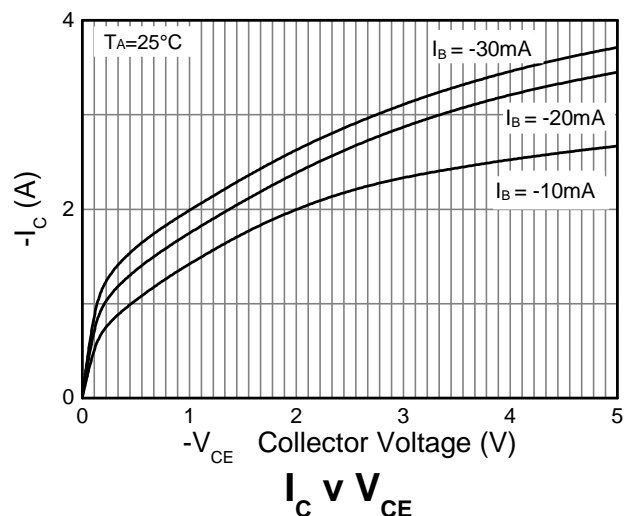
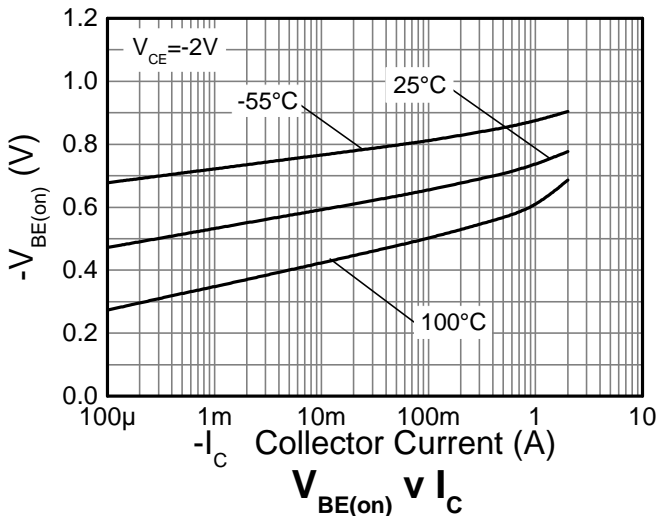
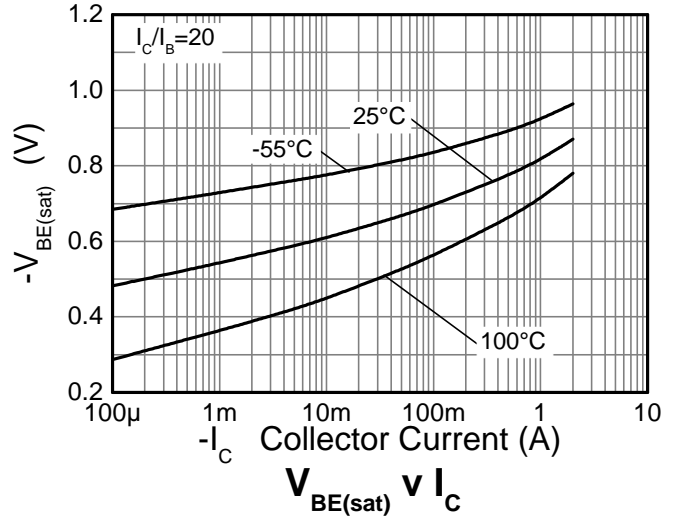
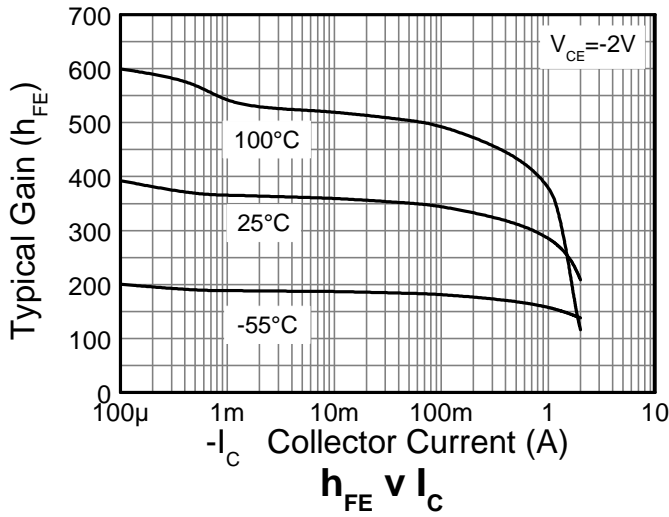
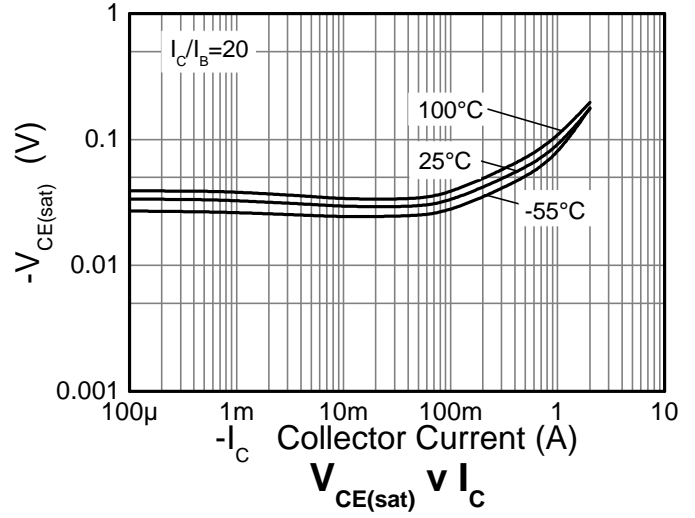
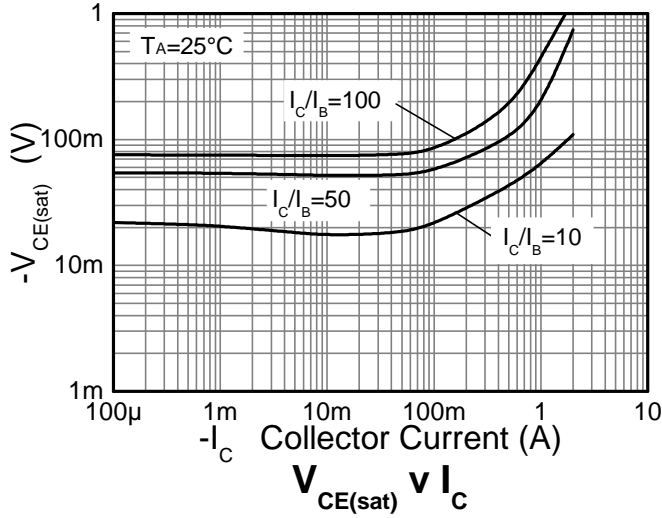


Electrical Characteristics (@T_A = +25°C, unless otherwise specified)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV _{CB0}	-100	—	—	V	I _C = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV _{CEO}	-100	—	—	V	I _C = -10mA
Emitter-Base Breakdown Voltage	BV _{EBO}	-7	—	—	V	I _E = -100μA
Collector Cutoff Current	I _{CB0}	—	—	-100	nA	V _{CB} = -80V
Emitter Cutoff Current	I _{EBO}	—	—	-100	nA	V _{EB} = -6V
Collector Emitter Cutoff Current	I _{CES}	—	—	-100	nA	V _{CES} = -80V
Static Forward Current Transfer Ratio (Note 8)	h _{FE}	160	260	—	—	I _C = -500mA, V _{CE} = -2V
		150	240	—		I _C = -1A, V _{CE} = -2V
		90	180	—		I _C = -2A, V _{CE} = -2V
		15	60	—		I _C = -3A, V _{CE} = -2V
Collector-Emitter Saturation Voltage (Note 8)	V _{CE(sat)}	—	-45	-70	mV	I _C = -0.5A, I _B = -50mA
		—	-95	-150		I _C = -1A, I _B = -50mA
		—	-125	-185		I _C = -2A, I _B = -200mA
Base-Emitter Turn-On Voltage (Note 8)	V _{BE(on)}	—	-0.75	-0.9	V	I _C = -2A, V _{CE} = -2V
Base-Emitter Saturation Voltage (Note 8)	V _{BE(sat)}	—	-0.75	-0.9	V	I _C = -1A, I _B = -10mA
Output Capacitance	C _{obo}	—	30	—	pF	V _{CB} = -10V, f = 1MHz
Transition Frequency	f _T	—	135	—	MHz	V _{CE} = -10V, I _C = -100mA, f = 100MHz
Delay Time	t _d	—	15	—	ns	V _{CC} = -9V, I _C = -2A I _{B1} = -I _{B2} = -0.1A
Rise Time	t _r	—	60	—		
Turn-On Time	t _{on}	—	75	—		
Storage Time	t _s	—	485	—		
Fall Time	t _f	—	155	—		
Turn-Off Time	t _{off}	—	640	—		

Note: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

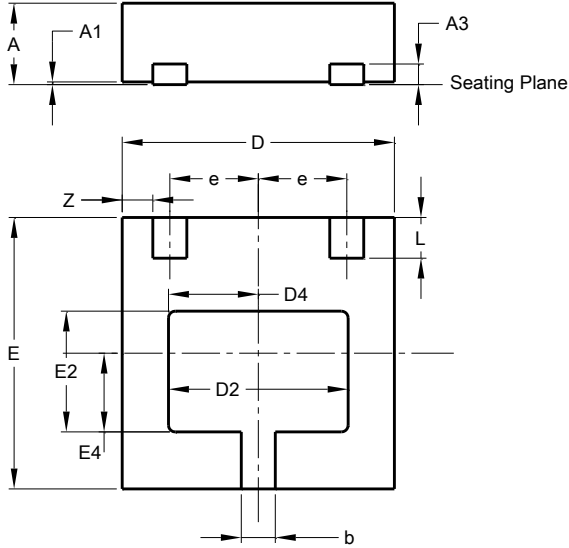
Typical Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)



Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-3 (Type B)

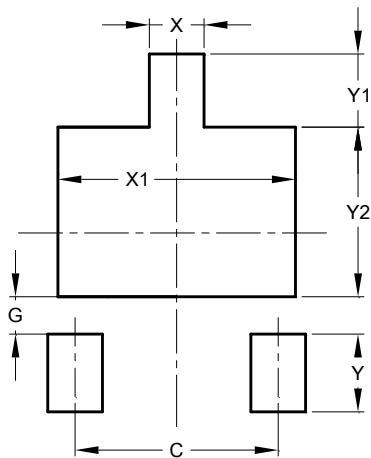


U-DFN2020-3 (Type B)			
Dim	Min	Max	Typ
A	0.57	0.63	0.60
A1	0.00	0.05	0.02
A3	—	—	0.152
b	0.20	0.30	0.25
D	1.950	2.075	2.00
D2	1.22	1.42	1.32
D4	0.56	0.76	0.66
E	1.950	2.075	2.00
E2	0.79	0.99	0.89
E4	0.48	0.68	0.58
e	—	—	0.65
L	0.25	0.35	0.30
Z	—	—	0.225
All Dimensions in mm			

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

U-DFN2020-3 (Type B)



Dimensions	Value (in mm)
C	1.300
G	0.240
X	0.350
X1	1.520
Y	0.500
Y1	0.470
Y2	1.090

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